L Number	Hits	Search Text	DB	Time stamp
1	323	219/448.11	USPAT; US-PGPUB; EPO; JPO;	2003/09/10 08:58
3	5	(219/448.11 and hot adj plate) and substrate	DERWENT; IBM_TDB USPAT;	2003/09/10
			US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	09:12
2	38	219/448.11 and hot adj plate	USPAT; US-PGPUB; EPO; JPO;	2003/09/10 09:20
4	11	(219/448.11 and hot adj plate) and cool\$3	DERWENT; IBM_TDB USPAT;	2003/09/10
			US-PGPUB; EPO; JPO; DERWENT;	09:08
5	3912	hot adj plate same substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/09/10 09:13
6	35	(hot adj plate same substrate) and	DERWENT; IBM_TDB USPAT;	2003/09/10
		temperature with means	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	09:15
7	1736	(hot adj plate same substrate) and cool\$3	USPAT; US-PGPUB; EPO; JPO;	2003/09/10 09:15
8	1654	((hot adj plate same substrate) and cool\$3)	DERWENT; IBM_TDB USPAT;	2003/09/10
		and temperature	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	09:20
9	901	(((hot adj plate same substrate) and cool\$3) and temperature) and substrate with thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/09/10 09:20
10	60	((((hot adj plate same substrate) and cool\$3) and temperature) and substrate with thickness) and resistive	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/09/10 09:38

11	29	((((hot adj plate same substrate) and	USPAT;	2003/09/10
		cool\$3) and temperature) and substrate with	US-PGPUB;	09:47
		thickness) and bottom adj plate	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	7	((((hot adj plate same substrate) and	USPAT;	2003/09/10
		cool\$3) and temperature) and substrate with	US-PGPUB;	09:47
		thickness) and bottom adj plate with hole	EPO; JPO;	
			DERWENT;	
			IBM_TDB	